| ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES® International and | <b>mposition De</b><br>5. IPC, Bannockl<br>Pan-American co  | <b>claration</b><br>ourn, Illinois. A<br>opyright conver | Il rights reserved u ntions. | nder both      | This docume<br>level parts, t                                       | ent is a declaration<br>he declaration er | on of the substancompasses all 1 | aces within the m<br>ower level materi | anufacturer l<br>ials for whicl | listed item. Note:<br>h the manufactur | if the item is an a<br>er has engineering | ssembly with low responsibility. |  |
|---|---|--|------------------------------|----------------|---|---|----------------------------------|--|---------------------------------|--|---|----------------------------------|--|
| 15,0_01   | IPC Web Site for Information on IPC-1752 Standard Form Ty<br>http://www.ipc.org/IPC-175x Distribution |  |                              |                | e * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |   |                                  |  | us Materials                    | ials and Mfg Information               |   |                                  |  |
| upplier Information   |   |  |                              |                |   |   |                                  |  |                                 |  |   |                                  |  |
| ompany name*  | Company un  | Company unique ID  |                              |                | Unique ID Authority   |   |                                  |  | Response Date*                  |  |   |                                  |  |
| nsemi   |   |  |                              |                |   |   |                                  |  | 2025-07-30                      |  |   |                                  |  |
| Contact Name Title  |   |  | Title - Contact              |                |   | Phone - Contact*                          |                                  |  |                                 | Email - Contact*                       |   |                                  |  |
| Product-Env-Stewards F  |   |  | Product Enviro Compliance    |                |   | NA  |                                  |  |                                 | Product-Env-Stewards@onsemi.com        |   |                                  |  |
| Authorized Representative* Tit                                      |   |  | Title - Representative       |                |   | Phone - Representative*                   |                                  |  | E                               | Email - Representative*                |   |                                  |  |
| roduct-Env-Stewards   | Product Enviro Compliance   |  |                              |                | NA  |   |                                  |  | Product-Env-Stewards@onsemi.com |  |   |                                  |  |
| Requester Item Number   |   |  | Number Mfr Item Name         |                |   | Effective Date                            | Version                          | Manufacturin                           | Manufacturing Site              |  | UOM                                       | Unit Type                        |  |
|   | MUR86   | MUR860G REC T0220 8                                      |                              | 8A 600V ULTFST |   | 2025-07-30                                |                                  | CN5                                    |                                 | 1962.01                                | mg  | Each                             |  |
| Ianufacturing Proccess Infor  | mation  |  |                              |                |   | •   | -                                |  |                                 |  |   |                                  |  |
| Terminal Plating / Grid Array                                       | Terminal Plating / Grid Array Material Terminal B   |  | Alloy J-STD-020 MSL          |                | L Rating  | Peak Process Body Temperature             |                                  | rature Max Tim                         | e at Peak Te                    | mperature Nun                          | ber of Reflow Cy                          | cles                             |  |
| Matte Tin (Sn) - annealed   |   | CU Alloy NA  |                              |                | 0 C   |   | 30                               |  | seconds 3                       |  |   |                                  |  |
| omments   |   |  |                              |                |   |   |                                  |  |                                 |  |   |                                  |  |
|   |   |  |                              |                |   |   |                                  |  |                                 |  |   |                                  |  |
| or more information regarding mate                                  | rial composition  | please refer to  | page 3                       |                |   |   |                                  |  |                                 |  |   |                                  |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *  | Detailed  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>ifies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the   | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst   | ances per the definition above except for sele   | ected exempt  | ions Supplier Acceptance  | * Accepted  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol   | der alloys containing 85% by weight or m   | ore lead).  |   |   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |   |  | e drop-dowi   | a. This will display the signature area. Digita   | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska  | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight  | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|---------|-----------------|----------|----------------------------|------------------|--------|---------|-----------------|
| Die                  | 3.55    | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 3.55    | mg              |
| Die Attach           | 82.98   | mg              | А        | Lead (Pb)                  | 7439-92-1        | 7a     | 74.682  | mg              |
|                      |         |                 | Supplier | Tin (Sn)                   | 7440-31-5        |        | 8.298   | mg              |
| Lead Frame           | 1300.04 | mg              | Supplier | Copper (Cu)                | 7440-50-8        |        | 1300.04 | mg              |
| Mold Compound-Black  | 543.9   | mg              |          | Metal Hydroxide            | proprietary data |        | 38.073  | mg              |
|                      |         |                 | Supplier | Carbon Black (C)           | 1333-86-4        |        | 2.7195  | mg              |
|                      |         |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 407.925 | mg              |
|                      |         |                 | Supplier | Ortho-Cresol Novolac Resin | 29690-82-2       |        | 81.585  | mg              |
|                      |         |                 | Supplier | Phenolic Resin (Novolac)   | 9003-35-4        |        | 13.5975 | mg              |
| Plating              | 31.13   | mg              | Supplier | Tin (Sn)                   | 7440-31-5        |        | 31.13   | mg              |
| Wire Bond - Al       | 0.41    | mg              | Supplier | Aluminum (Al)              | 7429-90-5        |        | 0.41    | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted)